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NV4V31SF

Preliminary Data Sheet

Specifications in this document are tentative and subject to change.

Blue-Violet Laser Diode

R08DS0070EJ0001

405 nm Blue-Violet Laser Light Source

Rev.0.01

Jan 24, 2013

DESCRIPTION

The NV4V31SF is a blue-violet laser diode with a wavelength of 405 nm. A newly developed LD chip structure achieves a high optical power output of 175 mW (CW). The NV4V31SF can provide excellent linearity from low to high output at high temperatures, and reduces the unevenness of beam divergence.

FEATURES

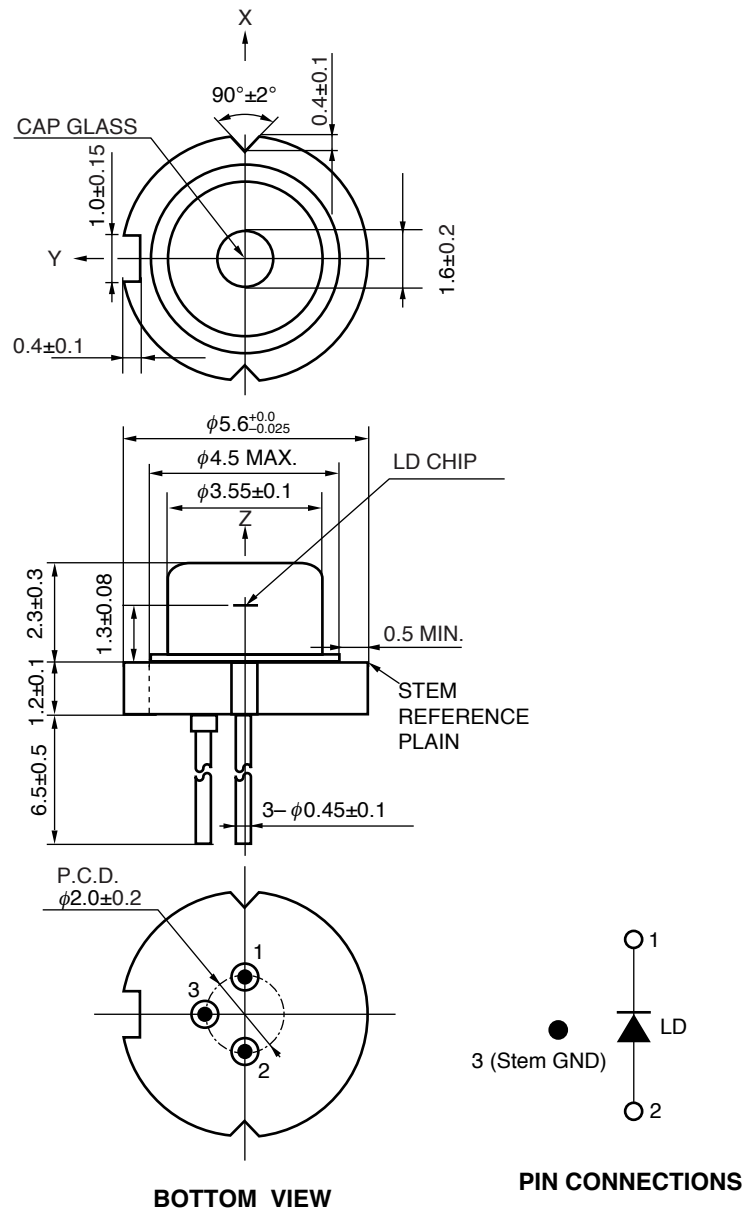
- High optical output power $P_o = 175 \text{ mW @CW}$
- Peak wavelength $\lambda_p = 405 \text{ nm TYP.}$
- Single transverse mode (lateral)
- Wide operating temperature range $T_C = - 5 \text{ to } +85^\circ\text{C}$
- $\phi 5.6 \text{ mm CAN package}$

APPLICATIONS

- Blue-violet laser light source



PACKAGE DIMENSIONS (UNIT: mm)



Remark Cap glass thickness : 0.25 ± 0.03 mm
 Cap glass refractive index : 1.53 ($\lambda = 405$ nm)

ORDERING INFORMATION

Part Number	Order Number	Rank	Package
NV4V31SF	NV4V31SF-A	HV	Tray Packaging (100 p/Tray)
		KV	Individual Packaging (for small samples)

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Optical Output Power (CW)	P_o	210	mW
Reverse Voltage of LD	V_R	2	V
Operating Case Temperature	T_C	-5 to +85	$^\circ\text{C}$
Storage Temperature	T_{stg}	-40 to +85	$^\circ\text{C}$

RECOMMENDED OPERATING CONDITIONS ($T_C = 25^\circ\text{C}$, unless otherwise specified)

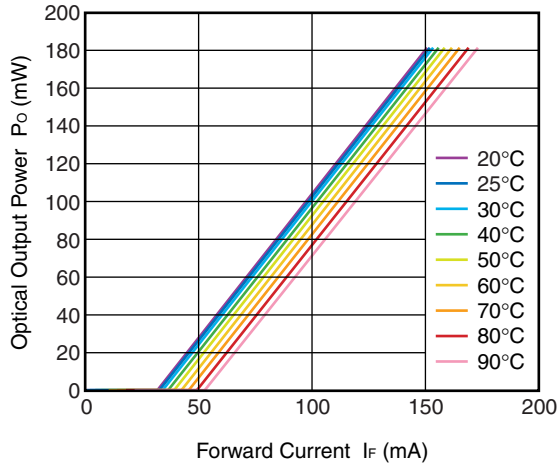
Parameter	Symbol	MAX.	Unit
Optical Output Power (CW)	P_o	175	mW

ELECTRO-OPTICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$, unless otherwise specified)

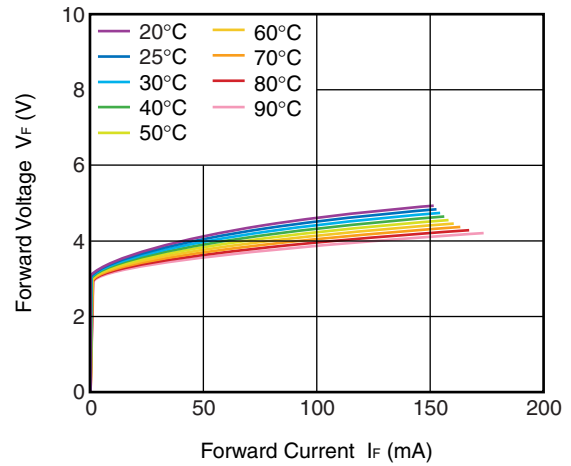
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Threshold Current	I_{th}	CW		35	55	mA
Operating Current	I_{op}	CW, $P_o = 175$ mW		150	200	mA
Operating Voltage	V_{op}	CW, $P_o = 175$ mW		5.0	6.5	V
Slope Efficiency	η_d	CW, $P_o = 20$ mW, 175 mW	1.1	1.55		W/A
Peak Wavelength	λ_p	CW, $P_o = 175$ mW	400	405	410	nm
Beam Divergence (lateral)	θ_l	CW, $P_o = 175$ mW	6	9	12	deg.
Beam Divergence (vertical)	θ_\perp		15	20	25	
Position Accuracy Angle (Horizontal)	$\Delta\theta_l$	CW, $P_o = 175$ mW	-3	0	3	deg.
Position Accuracy Angle (vertical)	$\Delta\theta_\perp$		-3	0	3	

TYPICAL CHARACTERISTICS
($T_c = 25^\circ\text{C}$, unless otherwise specified)

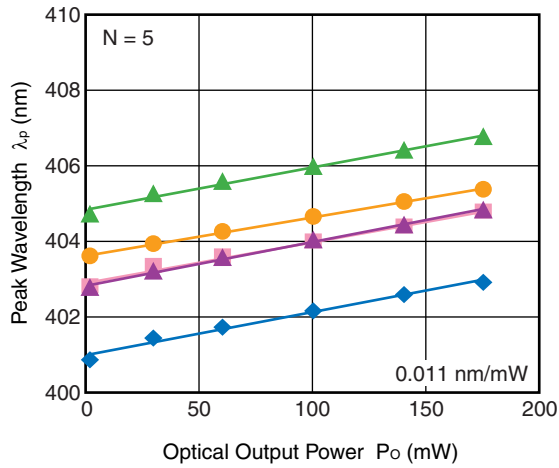
OPTICAL OUTPUT POWER vs. FORWARD CURRENT



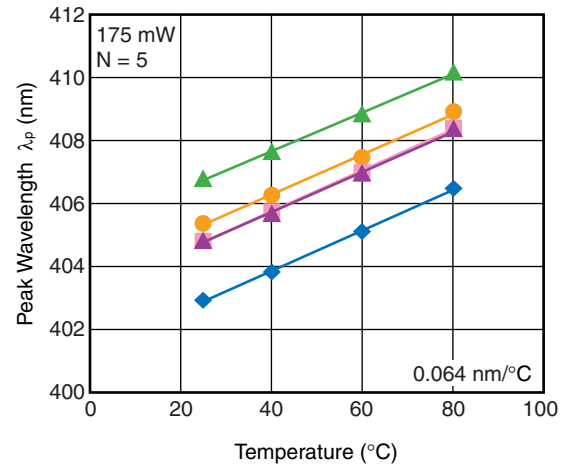
FORWARD VOLTAGE vs. FORWARD CURRENT



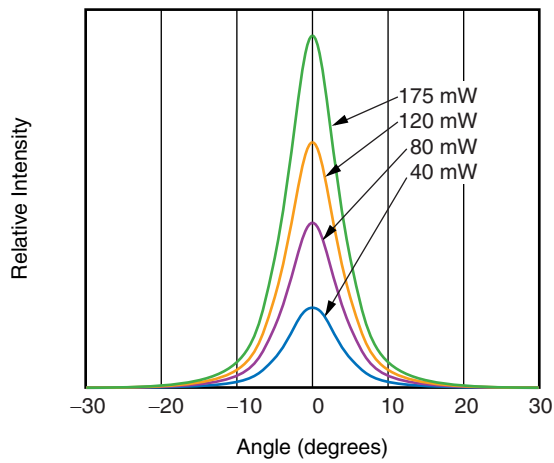
POWER DEPENDENCE OF PEAK WAVELENGTH



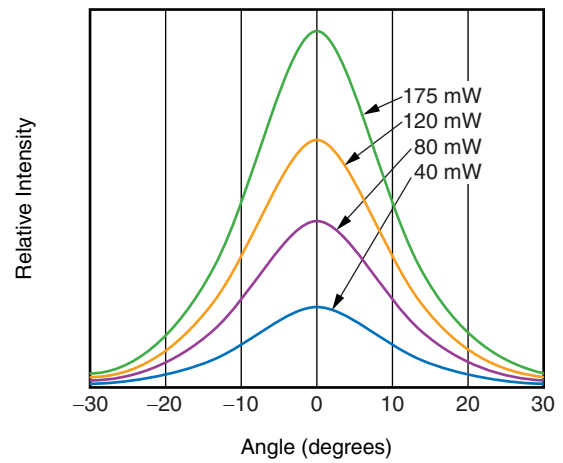
TEMPERATURE DEPENDENCE OF PEAK WAVELENGTH



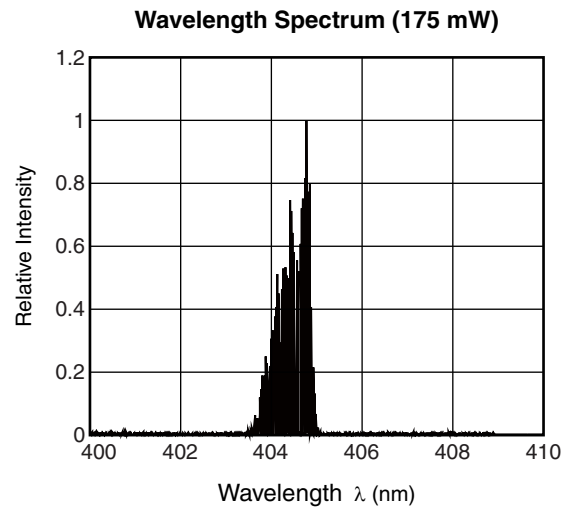
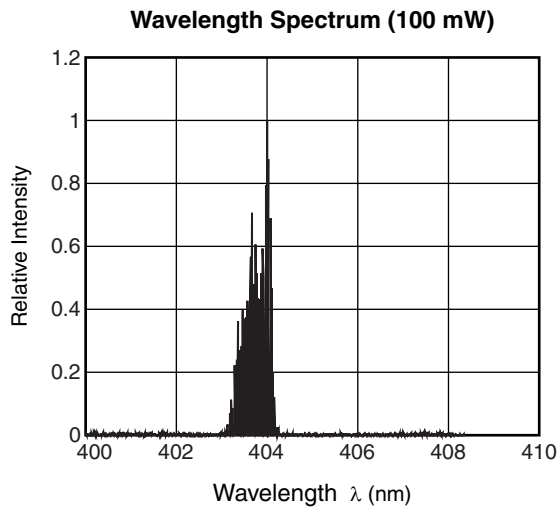
FFP (LATERAL)



FFP (VERTICAL)



Remark The graphs indicate nominal characteristics.



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NOTES ON HANDLING

1. Recommended soldering conditions

- Peak Temperature $\leq 350^{\circ}\text{C}$
- Time ≤ 3 seconds
- Soldering of leads should be made at the point 2.0 mm from the root of the lead
- This device cannot be mounted using reflow soldering.

2. Usage cautions

(1) Take the following steps to ensure that the device is not damaged by static electricity.

- Wear an antistatic wrist strap when soldering the device.
We recommend a strap with a 1 M Ω resistor.
- Make sure that the work table and soldering iron are grounded.
- Make sure that the soldering iron does not leak.

(2) Do not subject the package to undue stress.

The package has a tensile strength of 1N or less.

Do not exceed this rating. Also, avoid bending the leads as much as possible.

If the leads must be bent, bend them only once, making sure to anchor the stem base of the lead.

(3) Do not allow the cap glass of the package to become scratched or dirty.

Also, do not subject the cap glass to external force.

(4) Be sure to attach a heat sink to sufficiently dissipate heat.

(5) Use the device as soon as possible after opening the bag.

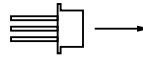
SAFETY INFORMATION ON THIS PRODUCT



VISIBLE LASER RADIATION
 AVOID EYE OR SKIN EXPOSURE TO
 DIRECT OR SCATTERED RADIATION

OUTPUT POWER 3W MAX
 WAVELENGTH 400 to 680nm
 CLASS IIIb LASER PRODUCT

SEMICONDUCTOR LASER



AVOID EXPOSURE-Invisible
 Laser Radiation is emitted from
 this aperture

<p>Warning Laser Beam</p>	<p>A laser beam is emitted from this diode during operation. If the laser beam or its reflection enters your eye, it may cause injury to the eye or loss of eyesight. (Note that, depending on the wavelength of the beam, the laser beam might not be visible.)</p> <ul style="list-style-type: none"> • Do not look directly into the laser beam. • Avoid exposure to the laser beam, any reflected or collimated beam.
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Revision History	NV4V31SF Preliminary Data Sheet
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Rev.	Date	Description	
		Page	Summary
0.01	Jan 24, 2013	-	First edition issued

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